

Title (en)

HIGH-DENSITY ELECTRICAL INTERCONNECT SYSTEM

Title (de)

ELEKTRISCHES VERBINDUNGS SYSTEM VON HOHER DICHTHE

Title (fr)

SYSTEME ELECTRIQUE D'INTERCONNEXIONS A HAUTE DENSITE

Publication

EP 0749639 A1 19961227 (EN)

Application

EP 95913542 A 19950309

Priority

- US 9502679 W 19950309
- US 20921994 A 19940311

Abstract (en)

[origin: WO9524748A1] An electrical interconnect system includes a support element; and an array of groups of multiple electrically conductive contacts arranged on the support element such that at least one contact of each group includes a front surface facing outwardly and away from that group along a line initially intersected by a side surface of a contact from another one of the groups of the array. The groups may be arranged in a configuration such that the array has a density of at least 500, 600, or 1,000 contacts per square inch.

IPC 1-7

H01R 13/26; **H01R 23/68**

IPC 8 full level

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CPC (source: EP)

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